

Ha
Amend
h. Chapman
8-29-00
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

SU et al.

Serial No.: 09/394,918

Filed: September 13, 1999

For: SUBSTRATE SAWING PROCESS FOR A STRIP



Group Art Unit: 3724

Examiner: O. Flores Sanchez

RECEIVED
AUG 23 2001
J 3700 MAIL ROOM

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is in response to the Official Action of April 11, 2000, in connection with the above-identified application. The period for response to this Official Action has been extended to expire on August 11, 2000, by the filing herewith of a Petition for a one-month extension of time and payment of the required fee.

Please amend the above-identified application as follows.

IN THE SPECIFICATION:

Please cancel the title and add the following new title to the application,
- -Process for Sawing Substrate Strip- -.

Page 1, line 4, after "sawing process", please cancel "for a strip";

line 5, please cancel "substrate sawing process by the multi-alignment on a strip" and insert -process for sawing a substrate strip having multi-alignment means thereon- -;

ar